

# Molding Type Module IGBT, 2 in 1 Package, 1200 V and 100 A



| PRODUCT SUMMARY                                |                  |  |  |  |  |
|--|------------------|--|--|--|--|
| V <sub>CES</sub>                               | 1200 V           |  |  |  |  |
| I <sub>C</sub> at T <sub>C</sub> = 80 °C       | 100 A            |  |  |  |  |
| $V_{CE(on)}$ (typical) at $I_C = 100$ A, 25 °C | 3.10 V           |  |  |  |  |
| Speed  | 8 kHz to 30 kHz  |  |  |  |  |
| Package  | Double INT-A-PAK |  |  |  |  |
| Circuit  | Half bridge      |  |  |  |  |

#### **FEATURES**

- NPT IGBT technology
- 10 µs short circuit capability
- · Low switching losses
- · Rugged with ultrafast performance
- V<sub>CE(on)</sub> with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **TYPICAL APPLICATIONS**

- · Switching mode power supplies
- · Inductive heating
- Electronic welder

#### **DESCRIPTION**

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welders and inductive heating.

| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C unless otherwise noted) |                                |                         |      |       |
|--|--------------------------------|-------------------------|------|-------|
| PARAMETER  | SYMBOL                         | TEST CONDITIONS         | MAX. | UNITS |
| Collector to emitter voltage   | V <sub>CES</sub>               |                         | 1200 | V     |
| Gate to emitter voltage  | V <sub>GES</sub>               |                         | ± 20 | V     |
| Collector current  | 1                              | T <sub>C</sub> = 25 °C  | 200  |       |
| Collector current  | Ic                             | T <sub>C</sub> = 80 °C  | 100  |       |
| Pulsed collector current   | I <sub>CM</sub> <sup>(1)</sup> | t <sub>p</sub> = 1 ms   | 200  | A     |
| Diode continuous forward current   | I <sub>F</sub>                 |                         | 100  |       |
| Diode maximum forward current  | I <sub>FM</sub> <sup>(1)</sup> |                         | 200  |       |
| Maximum power dissipation  | P <sub>D</sub>                 | T <sub>J</sub> = 150 °C | 1136 | W     |
| Isolation voltage  | V <sub>ISOL</sub>              | f = 50 Hz, t = 1 min    | 2500 | V     |

#### Note

<sup>(1)</sup> Repetitive rating: pulse width limited by maximum junction temperature.



| IGBT ELECTRICAL SPECIFICATIONS (T <sub>C</sub> = 25 °C unless otherwise noted) |                      |   |      |      |      |       |
|--|----------------------|---|------|------|------|-------|
| PARAMETER  | SYMBOL               | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNITS |
| Collector to emitter breakdown voltage   | V <sub>(BR)CES</sub> | T <sub>J</sub> = 25 °C  | 1200 | -    | -    |       |
| Calla stanta ansittan nalta sa   | V <sub>CF(on)</sub>  | V <sub>GE</sub> = 15 V, I <sub>C</sub> = 100 A, T <sub>J</sub> = 25 °C  | -    | 3.10 | 3.60 | ] ,   |
| Collector to emitter voltage   |                      | V <sub>GE</sub> = 15 V, I <sub>C</sub> = 100 A, T <sub>J</sub> = 125 °C | -    | 3.45 | -    | \ \   |
| Gate to emitter threshold voltage  | V <sub>GE(th)</sub>  | $V_{CE} = V_{GE}$ , $I_C = 1$ mA, $T_J = 25$ °C                         | 4.4  | 4.9  | 6.0  |       |
| Zero gate voltage collector current  | I <sub>CES</sub>     | $V_{CE} = V_{CES}$ , $V_{GE} = 0$ V, $T_{J} = 25$ °C                    | -    | -    | 5.0  | mA    |
| Gate to emitter leakage current  | I <sub>GES</sub>     | $V_{GE} = V_{GES}$ , $V_{CE} = 0$ V, $T_{J} = 25$ °C                    | -    | -    | 400  | nA    |

| PARAMETER                                | SYMBOL               | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNITS |
|--|----------------------|---|------|------|------|-------|
| Turn-on delay time                       | t <sub>d(on)</sub>   |   | -    | 300  | -    | - ns  |
| Rise time                                | t <sub>r</sub>       |   | -    | 64   | -    |       |
| Turn-off delay time                      | t <sub>d(off)</sub>  | $V_{CC} = 600 \text{ V}, I_{C} = 100 \text{ A}, R_{g} = 5.6 \Omega,$  | -    | 340  | -    |       |
| Fall time                                | t <sub>f</sub>       | $V_{GE} = \pm 15 \text{ V}, L = 200 \text{ nH}, T_{J} = 25 \text{ °C}$                                      | -    | 105  | -    |       |
| Turn-on switching loss                   | E <sub>on</sub>      |   | -    | 4.76 | -    | mJ    |
| Turn-off switching loss                  | E <sub>off</sub>     |   | -    | 4.25 | -    |       |
| Turn-on delay time                       | t <sub>d(on)</sub>   | $V_{CC}$ = 600 V, $I_{C}$ = 100 A, $R_{g}$ = 5.6 $\Omega$ , $V_{GE}$ = ± 15 V, L = 200 nH, $T_{J}$ = 125 °C | -    | 320  | -    | - ns  |
| Rise time                                | t <sub>r</sub>       |   | -    | 65   | -    |       |
| Turn-off delay time                      | t <sub>d(off)</sub>  |   | -    | 350  | -    |       |
| Fall time                                | t <sub>f</sub>       |   | -    | 132  | -    | ]     |
| Turn-on switching loss                   | E <sub>on</sub>      |   | -    | 7.20 | -    | 1     |
| Turn-off switching loss                  | E <sub>off</sub>     |   | -    | 5.50 | -    | - mJ  |
| Short circuit withstand time             | t <sub>SC</sub>      | T <sub>J</sub> = 125 °C   | -    | -    | 10   | μs    |
| Input capacitance                        | C <sub>ies</sub>     |   | -    | 8.45 | -    |       |
| Output capacitance                       | C <sub>oes</sub>     | V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 20 V, f = 1.0 MHz  | -    | 0.76 | -    | nF    |
| Reverse transfer capacitance             | C <sub>res</sub>     |   | -    | 0.31 | -    |       |
| SC data                                  | I <sub>SC</sub>      | $t_{p} \leq 10~\mu s,  V_{GE} = \pm~15~V,  V_{CC} = 600~V, \\ V_{CEM} \leq 1200~V,  T_{J} = 25~^{\circ}C$   | -    | 900  | -    |       |
| Internal gate resistance                 | R <sub>GINT</sub>    |   | -    | 2.4  | -    | Ω     |
| Stray inductance                         | L <sub>CE</sub>      |   | -    | -    | 18   | nH    |
| Module lead resistance, terminal to chip | R <sub>CC'+EE'</sub> |   | -    | 0.32 | -    | mΩ    |



| DIODE ELECTRICAL SPECIFICATIONS     |                  |  |                         |      |      |      |       |
|-------------------------------------|------------------|--|-------------------------|------|------|------|-------|
| PARAMETER                           | SYMBOL           | TEST CONDITIONS  |                         | MIN. | TYP. | MAX. | UNITS |
| Diode forward voltage               | .,               | I <sub>F</sub> = 100 A   | T <sub>C</sub> = 25 °C  | -    | 1.82 | 2.22 | V     |
| Diode forward voltage               | V <sub>F</sub>   |  | T <sub>C</sub> = 125 °C | -    | 1.95 |      | ]     |
| Diada rayaraa raaayany aharga       | Q <sub>rr</sub>  | 0  | T <sub>C</sub> = 25 °C  | -    | 5.4  | -    |       |
| Diode reverse recovery charge       |                  | Q <sub>rr</sub>  | T <sub>C</sub> = 125 °C | -    | 11.2 | -    | μC    |
| Diada pagk vayawa vagayaw ayawant   |                  | $I_F = 100 \text{ A}, V_R = 600 \text{ V},$                                | T <sub>C</sub> = 25 °C  | -    | 81   | -    | _     |
| Diode peak reverse recovery current | I <sub>rr</sub>  | $I_{rr}$ $dI_F/dt = -1900 \text{ A/}\mu\text{s},$ $V_{GE} = -15 \text{ V}$ | T <sub>C</sub> = 125 °C | -    | 101  | -    | A     |
| Diada wayawa waaayan anaway         | _                |  | T <sub>C</sub> = 25 °C  | -    | 3.54 | -    |       |
| Diode reverse recovery energy       | E <sub>rec</sub> |  | T <sub>C</sub> = 125 °C | -    | 6.57 | -    | - mJ  |

| THERMAL AND MECHANICAL SPECIFICATIONS |                     |                           |            |       |       |       |
|---------------------------------------|---------------------|---------------------------|------------|-------|-------|-------|
| PARAMETER                             | SYMBOL              | TEST CONDITIONS           | MIN.       | TYP.  | MAX.  | UNITS |
| Operating junction temperature range  | TJ                  |                           | -40        | -     | 150   | °C    |
| Storage temperature range             | T <sub>Stg</sub>    |                           | -40        | -     | 125   |       |
| Junction to case                      | - R <sub>thJC</sub> |                           | -          | -     | 0.141 |       |
| Diode                                 | □thJC               |                           | -          | -     | 0.225 | °C/W  |
| Case to sink                          | R <sub>thCS</sub>   | Conductive grease applied | -          | 0.035 | -     |       |
| Mounting torque                       |                     | Power terminal screw: M6  | 2.5 to 5.0 |       | Nm    |       |
|                                       |                     | Mounting screw: M6        | 3.0 to 6.0 |       | INIII |       |
| Weight                                |                     |                           |            | 300   | ·     | g     |

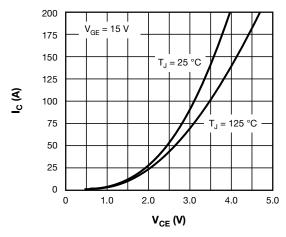


Fig. 1 - IGBT Typical Output Characteristics

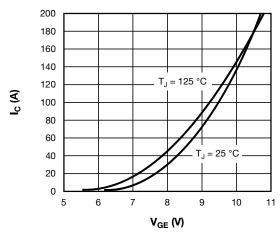


Fig. 2 - IGBT Typical Transfer Characteristics



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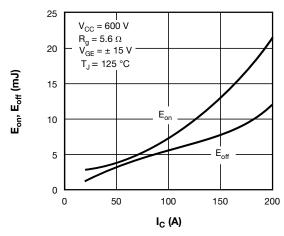


Fig. 3 - Switching Loss vs. I<sub>C</sub>

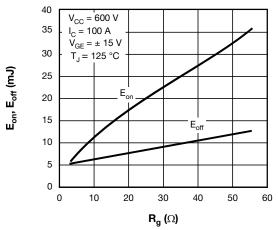


Fig. 4 - IGBT Switching Loss vs. Rq

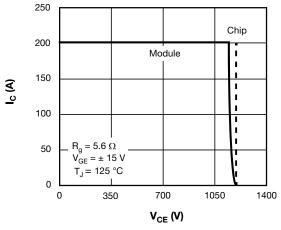


Fig. 5 - RBSOA

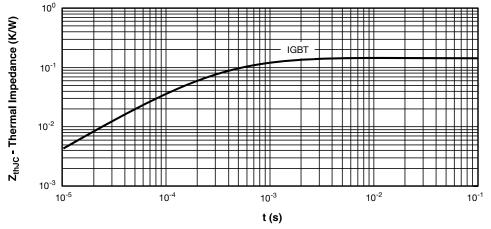


Fig. 6 - IGBT Transient Thermal Impedance



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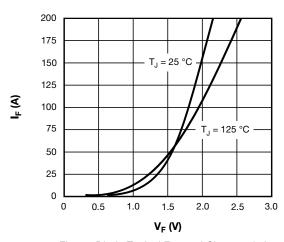


Fig. 7 - Diode Typical Forward Characteristics

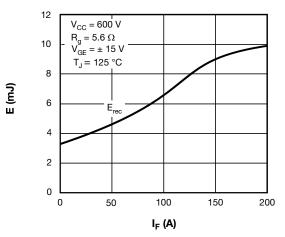


Fig. 8 - Diode Switching Loss vs. IF

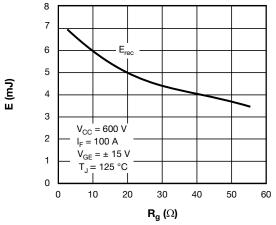


Fig. 9 - Diode Switching Loss vs. Rq

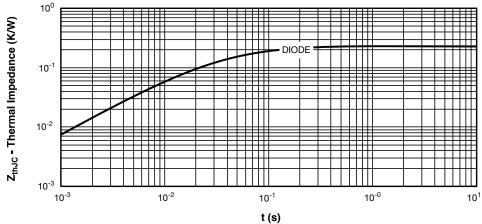
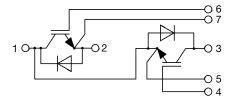


Fig. 10 - Diode Transient Thermal Impedance



### **CIRCUIT CONFIGURATION**

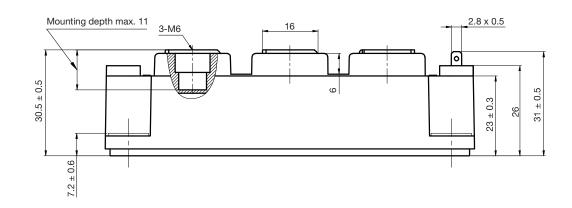


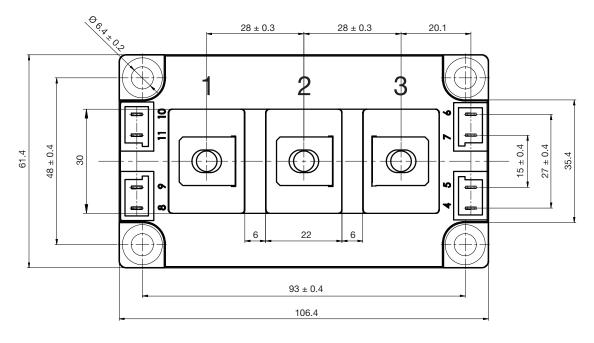
| LINKS TO RELAT | ED DOCUMENTS             |  |  |  |
|----------------|--------------------------|--|--|--|
| Dimensions     | www.vishay.com/doc?95525 |  |  |  |



### **Double INT-A-PAK**

### **DIMENSIONS** in millimeters (inches)







### **Legal Disclaimer Notice**

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